

**Amendments to the Specification:**

- (1) On page 1, delete the title and add the following new title:

METHOD OF MAKING CIRCUITIZED SUBSTRATE ASSEMBLY

- (2) On page 1, please delete the previously presented paragraph and subtitle in Applicants' Preliminary Amendment with the following new paragraph and subtitle:

**Cross Reference to Co-Pending Application**

This application is a divisional application of S.N. 10/322,527, entitled "Circuitized Substrate Assembly And Method Of Making Same", filed December 19, 2002 (Inventors: J. Fuller et al). S.N. 10/322,527 is now U.S. Patent 6,809,269, having issued 10/26/2004.

- (3) Please replace the last paragraph on page 7 with the following new paragraph:

In a preferred embodiment, a sticker sheet 31 is positioned between the respective substrates prior to lamination for the purpose of improving the bond between the substrates. The preferred sticker sheet material is defined hereinabove. It is understood, according to the broad aspects of the invention, that use of such a sticker sheet is not essential to achieve a satisfactory bond between the circuitized substrates taught herein. As clearly seen in FIG.1, the dielectric sticker sheet 31 does not physically engage conductive paste 25 prior to the bonding of the substrates. It cannot, therefore, provide support for the paste during the bonding steps.